TOSHIBA BIPOLAR DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

# TD62783AP,TD62783AFW,TD62784AP,TD62784AFW (Manufactured by Toshiba Malaysia)

#### 8CH HIGH-VOLTAGE SOURCE DRIVER

The TD62783AP / AFW Series are comprised of eight source current Transistor Array.

These drivers are specifically designed for fluorescent display applications.

Applications include relay, hammer and lamp drivers.

#### **FEATURES**

- High output voltage Type-AP, AFW :  $V_{CC} = 50 \text{ V MIN}$ . Type-F :  $V_{CC} = 35 \text{ V MIN}$ .
- Output current (single output) IOUT = -500 mA MIN.
- Output clamp diodes
- Single supply voltage
- Input compatible with various types of logic
- Package Type-AP : DIP-18 pinPackage Type-AFW: SOL-18 pin

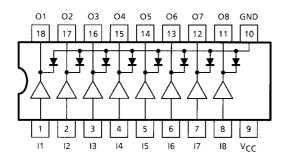
TYPE	DESIGNATION			
TD62783AP / AFW	TTL, 5 V CMOS			
TD62784AP / AFW	6~15 V PMOS, CMOS			

# TD62783AP TD62784AP DIP18-P-300-2.54F TD62783AFW TD62784AFW SOL18-P-300-1.27

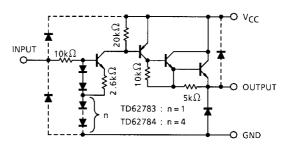
Weight

DIP18-P-300-2.54F: 1.478 g (Typ.) SOL18-P-300-1.27: 0.48 g (Typ.)

#### **PIN CONNECTION (TOP VIEW)**



#### **SCHEMATICS (EACH DRIVER)**



Note: The input and output parasitic diodes cannot be used as clamp diodes.



#### MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	RATING	UNIT	
Supply Voltage		V <sub>CC</sub>	50	V	
Output Current		lout	-500	mA / ch	
Input Voltage		V <sub>IN</sub> (Note 1)	15	V	
		V <sub>IN</sub> (Note 2)	30	V	
Clamp Diode Reverse V	np Diode Reverse Voltage		50	V	
Clamp Diode Forward C	mp Diode Forward Current		500	mA	
Power Dissipation	AP	P <sub>D</sub>	1.47	W	
	AFW	T PD	0.92 / 1.31 (Note 3)	VV	
Operating Temperature		T <sub>opr</sub>	-40~85	°C	
Storage Temperature		T <sub>stg</sub>	-55~150	°C	

Note 1: Only TD62783AP / AFW Note 2: Only TD62784AP / AFW

Note 3: On Glass Epoxy PCB (75  $\times$  114  $\times$  1.6 mm Cu 20%)

#### RECOMMENDED OPERATING CONDITIONS (Ta = $-40 \sim 85$ °C)

CHARACTERISTIC		SYMBOL	TEST CONDITION		MIN	TYP.	MAX	UNIT		
Supply V	oltage			V <sub>CC</sub>	V <sub>CC</sub> –		_	_	50	V
Output Current			Ta = 85°C	Duty = 10% 8Circuits		_	-260	mA /		
				Duty = 50% 8Circuits		_	-59			
			lout	$T_j = 120$ °C $T_{pw} = 25$ ms	Duty = 10% 8Circuits		_	-180	ch	
			AFW			Duty = 50% 8Circuits		_	-38	
Voltage		TD62783AP	/ AFW	V.	_			_	12	V
		TD62784AP	/ AFW	V <sub>IN</sub>	_			_	24	
	Output On	TD62783AP	/ AFW	V	_		2.0	5.0	15	V
Input		TD62784AP	/ AFW	V <sub>IN</sub> (ON)	_		4.5	12.0	30	
Voltage	Output Off	TD62783AP	/ AFW	V	_		0	_	0.8	
		TD62784AP	/ AFW	V <sub>IN (OFF)</sub>		0	_	2.0		
Clamp Diode Reverse Voltage AFW		AP	\/-	_		_	_	50	V	
		AFW	$V_{R}$	_		_	_	35		
Clamp Diode Forward Current		I <sub>F</sub>	_		_	_	400	mA		
Power Dissipation AP AFW		D-	Ta = 85°C	Ta = 85°C		_	0.76	w		
		AFW	$P_{D}$	Ta = 85°C (Note)		_	_	0.48	V V	

Note: On Glass Epoxy PCB (75 × 114 × 1.6 mm Cu 20%)



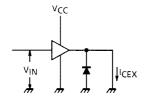
## **ELECTRICAL CHARACTERISTICS (Ta = 25°C)**

CHARACTERISTIC		SYMBOL	TEST CIR- CUIT	TEST CONDITION	MIN	TYP.	MAX	UNIT
Output Leakage	Output Leakage Current		1	V <sub>CC</sub> = V <sub>CC MAX</sub> . V <sub>IN</sub> = 0.4 V Ta = 25°C	-	_	100	μΑ
Output Saturation Voltage		V <sub>CE</sub> (sat)	2	$V_{IN} = V_{IN (ON)},$ $I_{OUT} = -350 \text{ mA}$	-	_	2.0	V
				V <sub>IN</sub> = V <sub>IN</sub> (ON), I <sub>OUT</sub> = -225 mA	-	_	1.9	
				V <sub>IN</sub> = V <sub>IN</sub> (ON), I <sub>OUT</sub> = -100 mA	-	_	1.8	
Input Current	TD62783AP / AFW	lin (On)	3	V <sub>IN</sub> = 2.4 V	_	36	52	- - μΑ
				V <sub>IN</sub> = 3.85 V	_	180	260	
	TD62784AP / AFW			V <sub>IN</sub> = 5 V	_	92	130	
				V <sub>IN</sub> = 12 V	_	790	1130	
	TD62783AP / AFW	V	- 4	V <sub>CE</sub> = 2.0 V	_	_	2.0	V
Innut Valtage	TD62784AP / AFW	V <sub>IN</sub> (ON)		I <sub>OUT</sub> = −350 mA	_	_	4.5	
Input Voltage	TD62783AP / AFW	M		I <sub>OUT</sub> = -500 μA	0.8	_	_	
	TD62784AP / AFW	V <sub>IN (OFF)</sub>			2.0	_	_	
Supply Current		I <sub>CC (ON)</sub>	3	V <sub>IN</sub> = V <sub>IN (ON)</sub> , V <sub>CC</sub> = 50 V	_	_	2.5	mA / ch
Clamp Diode Reverse Current		I <sub>R</sub>	5	V <sub>R</sub> = 50 V	_	_	50	μΑ
Clamp Diode Forward Voltage		V <sub>F</sub>	6	I <sub>F</sub> = 350 mA	_	_	2.0	V
Turn-On Delay		ton	7	$V_{CC} = V_{CC \text{ MAX.}} R_L = 125 \Omega$ $C_L = 15 \text{ pF}, R_L = 88 \Omega (F)$	_	0.15	_	μs
Turn-Off Delay		tOFF	<u> </u>		_	1.8	_	

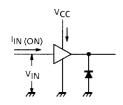
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#### **TEST CIRCUIT**

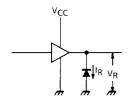
#### 1. ICEX



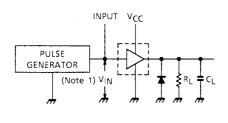
#### 3. I<sub>IN (ON)</sub>, I<sub>CC</sub>



#### 5. I<sub>R</sub>



#### 7. ton, toff

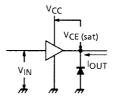


Note 1: Pulse width 50  $\mu s,\,duty$  cycle 10%

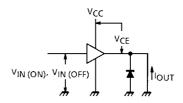
Output impedance 50  $\Omega$ ,  $t_r \le 5$  ns,  $t_f \le 10$  ns

Note 2: C<sub>L</sub> includes probe and jig capacitance

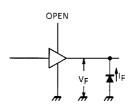
### 2. VCE (sat)

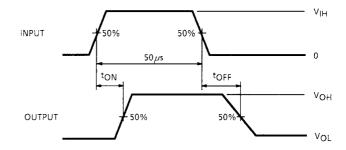


#### 4. V<sub>IN (ON)</sub>, V<sub>IN (OFF)</sub>



#### 6. V<sub>F</sub>



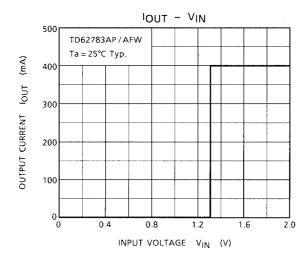


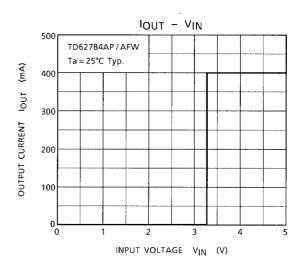
#### PRECAUTIONS for USING

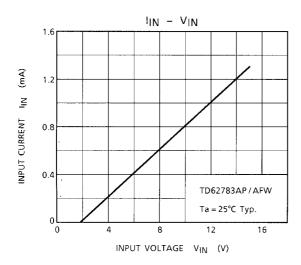
This IC does not integrate protection circuits such as overcurrent and overvoltage protectors.

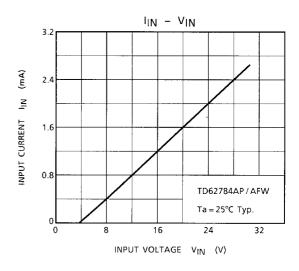
Thus, if excess current or voltage is applied to the IC, the IC may be damaged. Please design the IC so that excess current or voltage will not be applied to the IC.

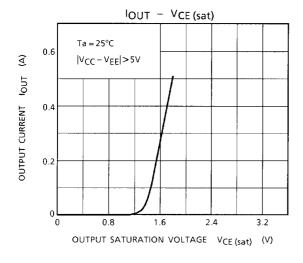
Utmost care is necessary in the design of the output line,  $V_{CC}$  and GND line since IC may be destroyed due to short–circuit between outputs, air contamination fault, or fault by improper grounding.

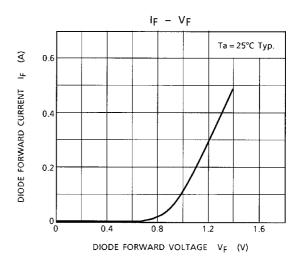


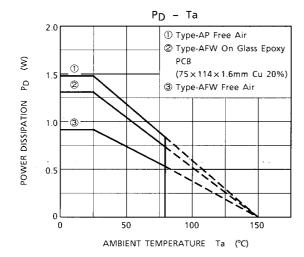








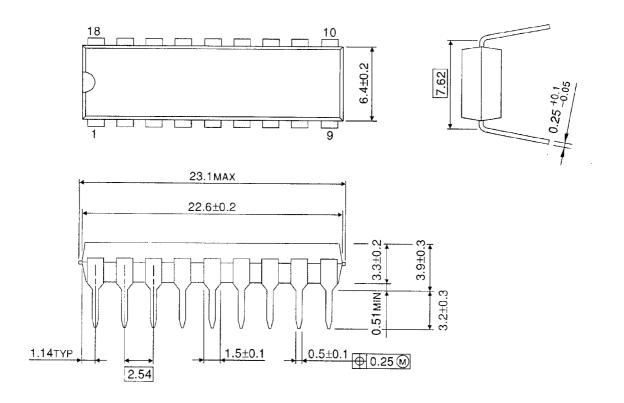




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#### **PACKAGE DIMENSIONS**

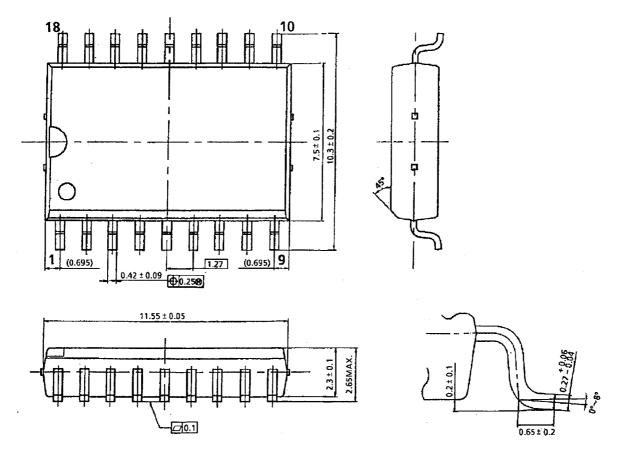
DIP18-P-300-2.54F Unit: mm



Weight: 1.478 g (Typ.)

#### **PACKAGE DIMENSIONS**

SOL18-P-300-1.27 Unit: mm



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Weight: 0.48 g (Typ.)

#### RESTRICTIONS ON PRODUCT USE

000707EBA

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